2.0x1.25mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APHBM2012LQBDCGKC

Blue Green

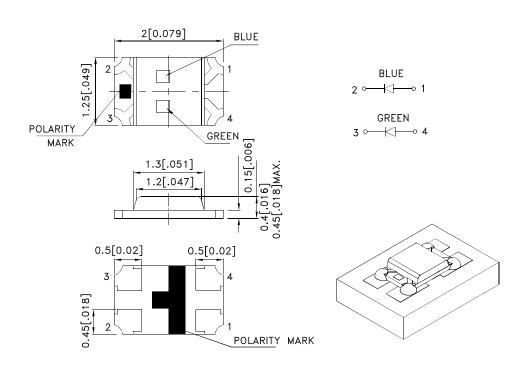
Features

- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Blue source color devices are made with InGaN Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAO4528 **REV NO: V.1B** DATE: AUG/01/2015 PAGE: 1 OF 6 **APPROVED: Wynec** CHECKED: Allen Liu DRAWN: M.Liu ERP: 1203015144

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHBM2012LQBDCGKC	Blue (InGaN)	Water Clear	6	12	120°
	Green (AlGalnP)	Water Clear	1.2	2	

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous Flux: +/-15%.
 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Min.	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Blue Green		460 574		nm	IF=2mA	
λD [1]	Dominant Wavelength	Blue Green		465 570		nm	IF=2mA	
Δλ1/2	Spectral Line Half-width	Blue Green		25 20		nm	IF=2mA	
С	Capacitance	Blue Green		100 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Blue Green	2.2 1.5	2.65 1.9	3 2.1	V	IF=2mA	
lr	Reverse Current	Blue Green			50 10	uA	VR = 5V	

Notes:

- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

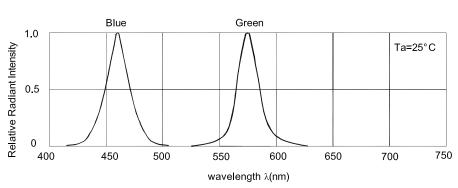
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Green	Units		
Power dissipation	90	63	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	150	150	mA		
Electrostatic Discharge Threshold (HBM)	250	3000	V		
Reverse Voltage	5		V		
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

Note:

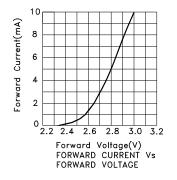
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

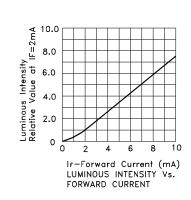
SPEC NO: DSAO4528 **REV NO: V.1B** DATE: AUG/01/2015 PAGE: 2 OF 6 APPROVED: Wynec **CHECKED: Allen Liu** DRAWN: M.Liu ERP: 1203015144

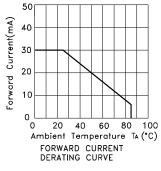


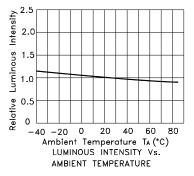
Relative Intensity Vs. Wavelength

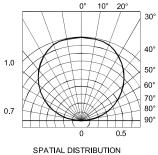
APHBM2012LQBDCGKC Blue







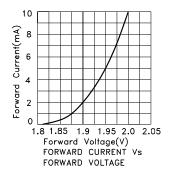


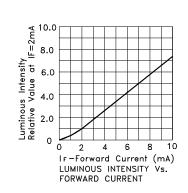


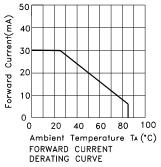
 SPEC NO: DSAO4528
 REV NO: V.1B
 DATE: AUG/01/2015
 PAGE: 3 OF 6

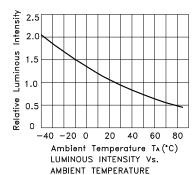
 APPROVED: Wynec
 CHECKED: Allen Liu
 DRAWN: M.Liu
 ERP: 1203015144

Green



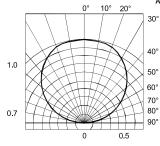






PAGE: 4 OF 6

ERP: 1203015144



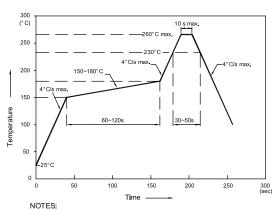
SPATIAL DISTRIBUTION

SPEC NO: DSAO4528 REV NO: V.1B DATE: AUG/01/2015
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu

APHBM2012LQBDCGKC

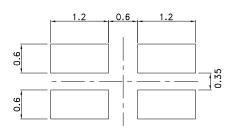
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



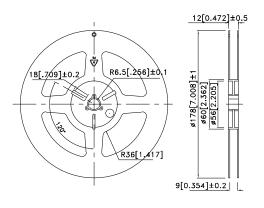
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed $% \left(1\right) =\left(1\right) \left(1\right)$
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

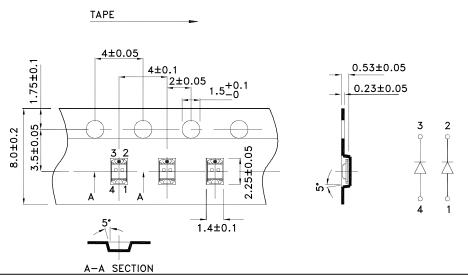
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

Reel Dimension



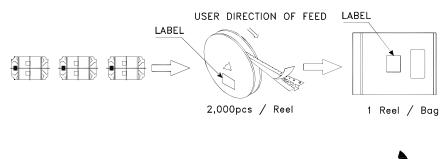


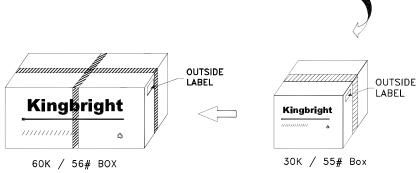
 SPEC NO: DSAO4528
 REV NO: V.1B
 DATE: AUG/01/2015
 PAGE: 5 OF 6

 APPROVED: Wynec
 CHECKED: Allen Liu
 DRAWN: M.Liu
 ERP: 1203015144

PACKING & LABEL SPECIFICATIONS

APHBM2012LQBDCGKC







Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6. All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

SPEC NO: DSAO4528 REV NO: V.1B DATE: AUG/01/2015 PAGE: 6 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu ERP: 1203015144